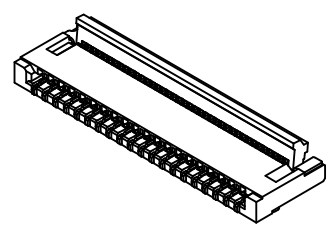
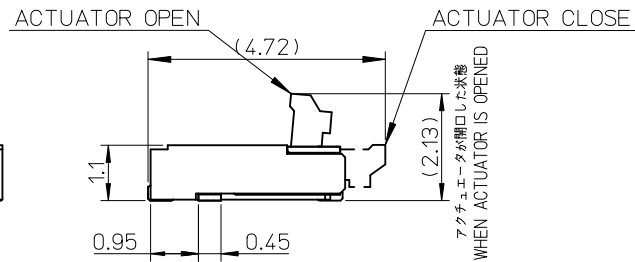


SECTION Z-Z SECTION Y-Y



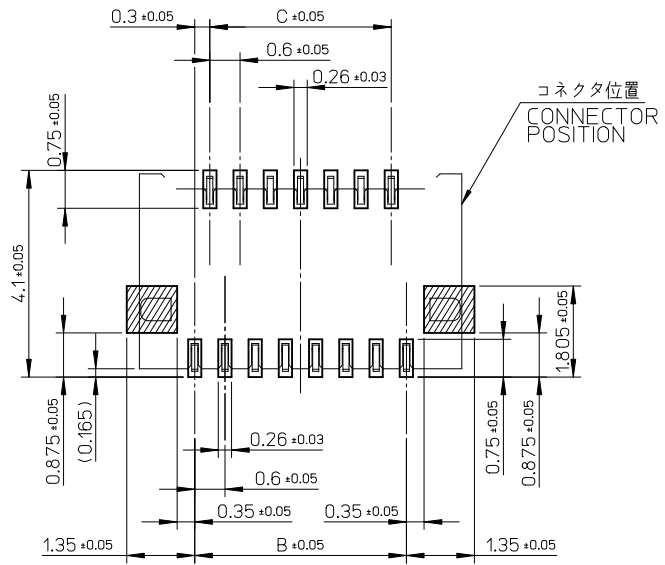
斜視図
SCALE 5:1

- 部品構成 MATERIAL
- ハウジング: 液晶ポリマー(LCP)、ガラス充填、ナチュラル、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED, NATURAL UL94V-0
 - 奇数ターミナル: リン青銅
ODD TERMINAL: PHOSPHOR BRONZE
処理: ニッケル下地(1.0μm以上)
コンタクト部: 部分金メッキ(0.1μm以上)
テール部: 部分金メッキ
ニッケルストライプ(バリア)
FINISH: OVER NICKEL PLATING (1.0 MICROMETER MINIMUM)
CONTACT AREA: SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)
SOLDER TAIL AREA: SEPARATED GOLD PLATING
NI STRIPE(BARRIER)
 - 偶数ターミナル: リン青銅
EVEN TERMINAL: PHOSPHOR BRONZE
処理: ニッケル下地(1.0μm以上)
コンタクト部: 部分金メッキ(0.1μm以上)
テール部: 部分金メッキ
ニッケルストライプ(バリア)
FINISH: OVER NICKEL PLATING (1.0 MICROMETER MINIMUM)
CONTACT AREA: SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)
SOLDER TAIL AREA: SEPARATED GOLD PLATING
NI STRIPE(BARRIER)
 - アクチュエータ: ポリアミド(PA)、ガラス充填、黒色、UL94V-0
ACTUATOR: POLYAMIDE(PA), GLASS FILLED, BLACK, UL94V-0
 - ネイル: リン青銅
NAIL: PHOSPHOR BRONZE
処理: ニッケル下地すずめっき
FINISH: TIN OVER NICKEL PLATING

15.6	14.4	15.0	17.2	502350-5110	51
14.4	13.2	13.8	16.0	502350-4710	47
13.8	12.6	13.2	15.4	502350-4510	45
12.6	11.4	12.0	14.2	502350-4110	41
12.0	10.8	11.4	13.6	502350-3910	39
11.4	10.2	10.8	13.0	502350-3710	37
10.2	9.0	9.6	11.8	502350-3310	33
9.6	8.4	9.0	11.2	502350-3110	31
7.2	6.0	6.6	8.8	502350-2310	23
6.0	4.8	5.4	7.6	502350-1910	19
4.8	3.6	4.2	6.4	502350-1510	15
D	C	B	A	EMBOSSED TAPE	CIRCUITS
				ORDER NO. オーダー番号	

CONNECTOR SERIES NO. 502350-**-19

RELEASED EC NO: J2012-1261 DRWN:SHIRATA 2012/03/26 CHKD:YKOBAYASHI02 2012/03/26 APPR:KMORIKAWA 2012/03/27	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY SHIRATA	DATE 2012/03/26	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE		
	10 OVER 30 UNDER	±0.25	CHECKED BY YKOBAYASHI02	DATE 2012/03/26	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2012/03/27	DOCUMENT NO. SD-502350-003		
	ANGULAR	±3 °	MATERIAL NO.	SEE CHART	SHEET NO. 1 OF 2		
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN DIM.(REF.)

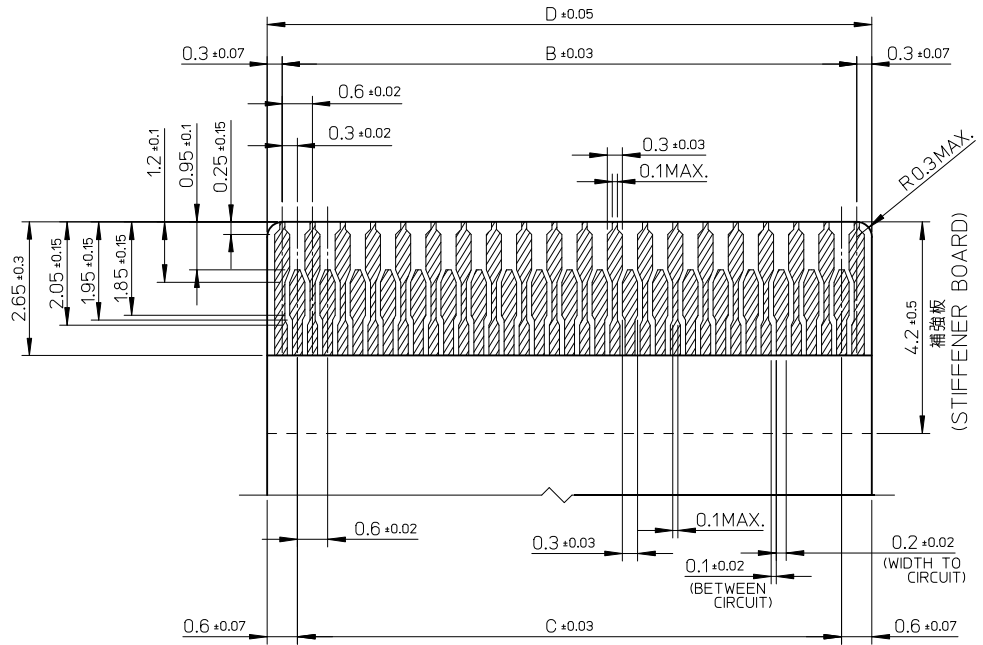
推奨メタルマスク厚さ : 0.1mm
 RECOMMENDED METAL MASK THICKNESS : 0.1mm
 推奨開口率 : 100%
 APERTURE RATE : 100%

注記
 NOTE

1. 基板実装前にアクチュエータを操作しないで下さい。
 PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
2. 必ず基板に実装してからアクチュエータを操作して下さい。
 PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
3. FPCについて
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
 ABOUT FPC
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。
 導体部については軟銅箔35μmまたは50μmを推奨致します。
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPECIFICATION:
 THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER

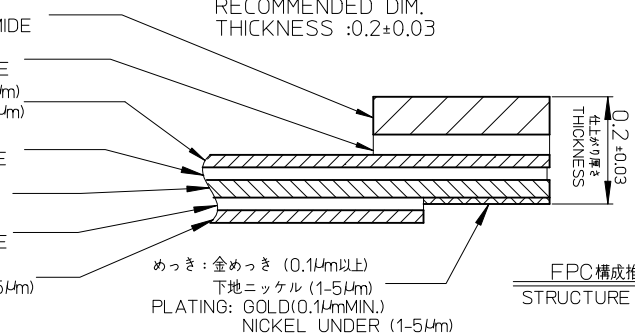
4. 平坦度は0.1以下
 COPLANARITY TO BE 0.1 MAXIMUM
5. 502350-***19限定形状
 ONLY USED BY 502350-***19
6. ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT



適合FPC推奨寸法

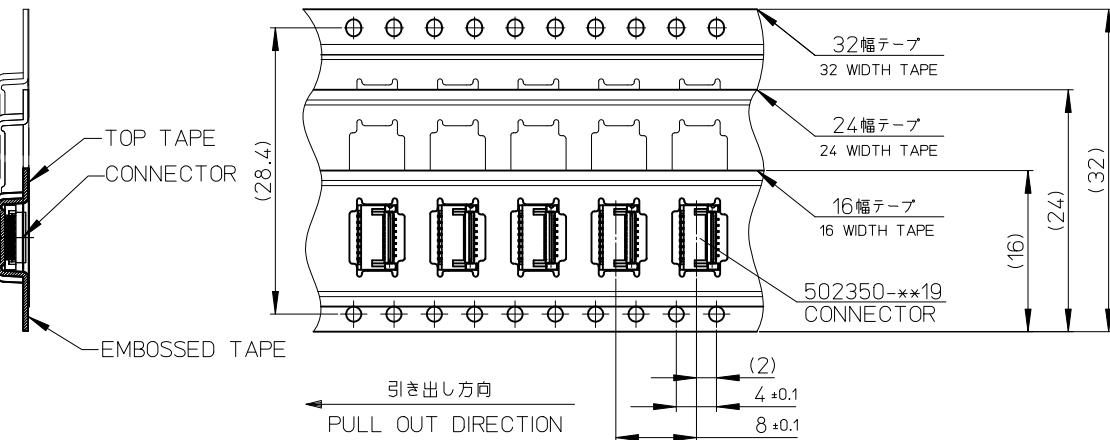
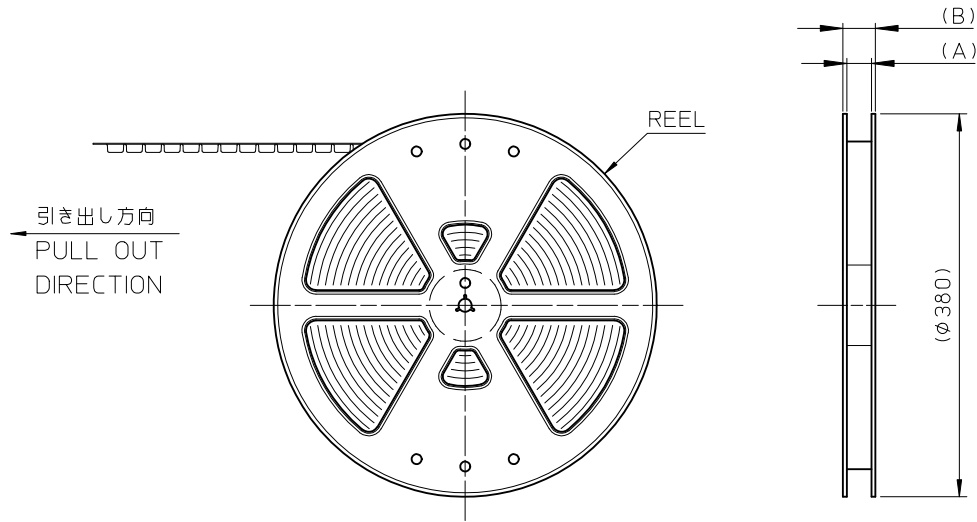
仕上がり厚さ : 0.2±0.03
 APPLY FPC
 RECOMMENDED DIM.
 THICKNESS : 0.2±0.03

- 補強板: ポリイミド
 REINFORCE BOARD: POLYIMIDE
- 熱硬化接着剤
 THERMOSETTING ADHESIVE
- ベースフィルム: ポリイミド (25μm)
 BASE FILM: POLYIMIDE (25μm)
- 熱硬化接着剤
 THERMOSETTING ADHESIVE
- 導体部: 銅箔 (35μm)
 COPPER FOIL (35μm)
- 熱硬化接着剤
 THERMOSETTING ADHESIVE
- カバーレイ: ポリイミド (25μm)
 COVER FILM: POLYIMIDE (25μm)



FPC構成推奨仕様
 STRUCTURE OF FPC

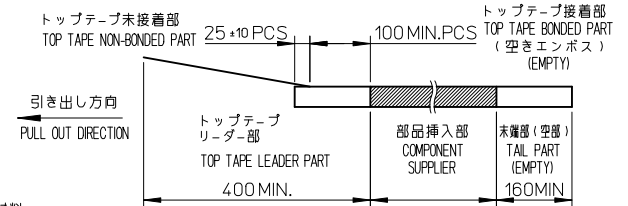
RELEASED EC NO.: J2012-1261 DRWN: SHIRATA CHKD: YKOBAYASHI02 APPR: KMORIKAWA 2012/03/26 2012/03/26 2012/03/27	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY SHIRATA	DATE 2012/03/26	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE		
	10 OVER 30 UNDER	±0.25	CHECKED BY YKOBAYASHI02	DATE 2012/03/26	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2012/03/27			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		DOCUMENT NO. SD-502350-003	SHEET NO. 2 OF 2
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



エンボステープ内の製品の向き
DIRECTION OF CONNECTOR IN
EMBOSSED TAPE

NOTES

- 製品 (502350-**19) の詳細寸法については、図面 SD-502350-003をご参照下さい。
IN THE PACKAGE, PART NO. 502350-**19 DETAILED DIMENSIONS.
REFER TO SALES DRAWING NO. SD-502350-003.
- 梱包数量 : 3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
キャリアテープ : ポリスチレン (PS)
トップテープ : PET, OTHER
リール : ポリスチレン (PS) <リサイクル材を含む>
MATERIAL
CARRIER TAPE : POLYSTYRENE(PS)
TOP TAPE : PET, OTHER
REEL : POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- トップテープの剥離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

37.4	33.4	32	502350-5110	51
			502350-4710	47
29.4	25.4	24	502350-4510	45
			502350-4110	41
			502350-3910	39
			502350-3710	37
			502350-3310	33
			502350-3110	31
			502350-2310	23
			502350-1910	19
21.4	17.4	16	502350-1510	15
B	A	WIDTH TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUIT
502350-**10			MODEL NO.	

RELEASED EC NO.: J2012-1261 DRWN:SHIRATA 2012/03/26 CHKD:YKOBAYASHI02 2012/03/26 APPR:KMORIKAWA 2012/03/27	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY SHIRATA	DATE 2012/03/26	TITLE 0.3 FPC CONN. H=1.1 EMBSTP PKG				
		10 OVER 30 UNDER	± 0.25	CHECKED BY YKOBAYASHI02	DATE 2012/03/26	MOLEX INCORPORATED SEE CHART SD-502350-004 1 OF 1				
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2012/03/27					
		ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-502350-004		SHEET NO. 1 OF 1
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										